

PRESS RELEASE

Lasertec Corporation

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Lasertec to deliver 10th “SICA88 Series” SiC wafer inspection/review system in one year since its market release

Yokohama, Japan, November 7, 2016 – **Lasertec Corporation** announced today that it is now scheduled to ship the 10th unit of SICA88 Series (volume production tool) SiC wafer inspection/review system released in September 2015. SICA88 Series has reached this milestone in merely one year since its official release.

Demand for the next generation power devices is booming as the need for higher energy efficiency is growing rapidly. Among them, SiC devices play an important role in power electronics market. Automobile makers are actively pursuing the use of SiC devices in cars because they offer such merits as downsizing and small power loss. Seeing this as a trigger to large market growth, SiC substrate manufacturers and SiC device manufacturers in Japan, Europe and elsewhere worldwide are accelerating development efforts in order to start the full-fledged volume production in around 2020.

A major challenge for these manufacturers is to make SiC devices less expensive and more efficient. In supporting their efforts, SICA88 Series has earned a high reputation as a tool that enables dramatic increase in SiC wafer quality. As a result, it has achieved an order for the 10th delivery in just one year since its market release. SICA88 Series has both wafer surface inspection and photoluminescence inspection in one platform enabling the detection of surface defects and defects buried inside. It is also capable of performing a high precision automatic defect classification (ADC) while capturing high resolution review images at the same time. SICA88 Series is making contributions in such areas as quality control and product rating by SiC wafer manufacturers and production technology development and incoming wafer inspection by SiC device manufacturers.

“Major SiC related manufacturers in Japan including ROHM Co., Ltd. and Showa Denko K.K. have adopted SICA88 Series,” said Hirokazu Seki, General Manager of Technology Department 1 at Lasertec. “Multiple industry leaders in Europe and the United States have also taken the delivery of SICA88 Series. We are receiving many more inquiries about the system. The number of customers who introduce a second or third unit is also increasing. The fact that many customers have adopted SICA88 in such a short period is a testament that SICA brings great benefits to them. With SiC devices entering into volume production, a rapid market growth is forecast. Lasertec will contribute to the improvement of SiC device quality by providing SICA88.”

About Lasertec

As a leader in metrology and inspection tooling, Lasertec Corporation has been serving the needs of semiconductor, compound semiconductor, renewable energy, FPD and other high technology industries for many years. Since its beginning in 1960, Lasertec has been evolving and growing to keep pace with the world’s rapidly expanding and changing high technology manufacturing requirements. In addition to the innovative technologies, Lasertec’s global support infrastructure assures customers full satisfaction through high tool availability that maximizes the capital investment and device yield. For more information, go to www.lasertec.co.jp/en.

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